



SOT1762-2

SSOP32; plastic, shrink small outline package; 32 terminals;
0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

15 January 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP32
Package type industry code	SSOP32
Package style descriptive code	SSOP (shrink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-01-2016
Manufacturer package code	98ASA00259D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7.5	-	mm
package width	-	11	-	mm
seated height	-	2.3	2.45	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	32	-	



SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

2 Package outline

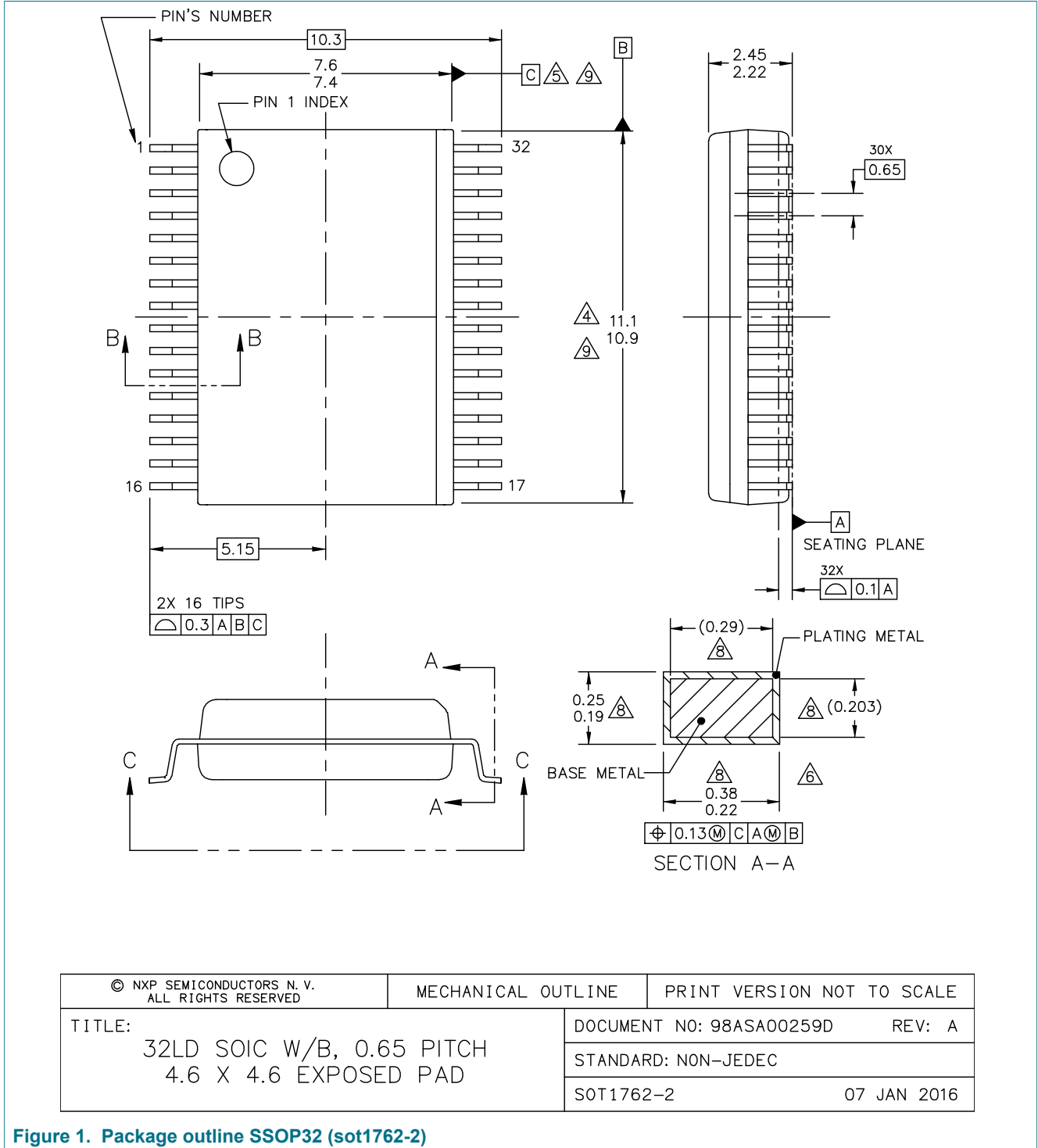


Figure 1. Package outline SSOP32 (sot1762-2)

SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

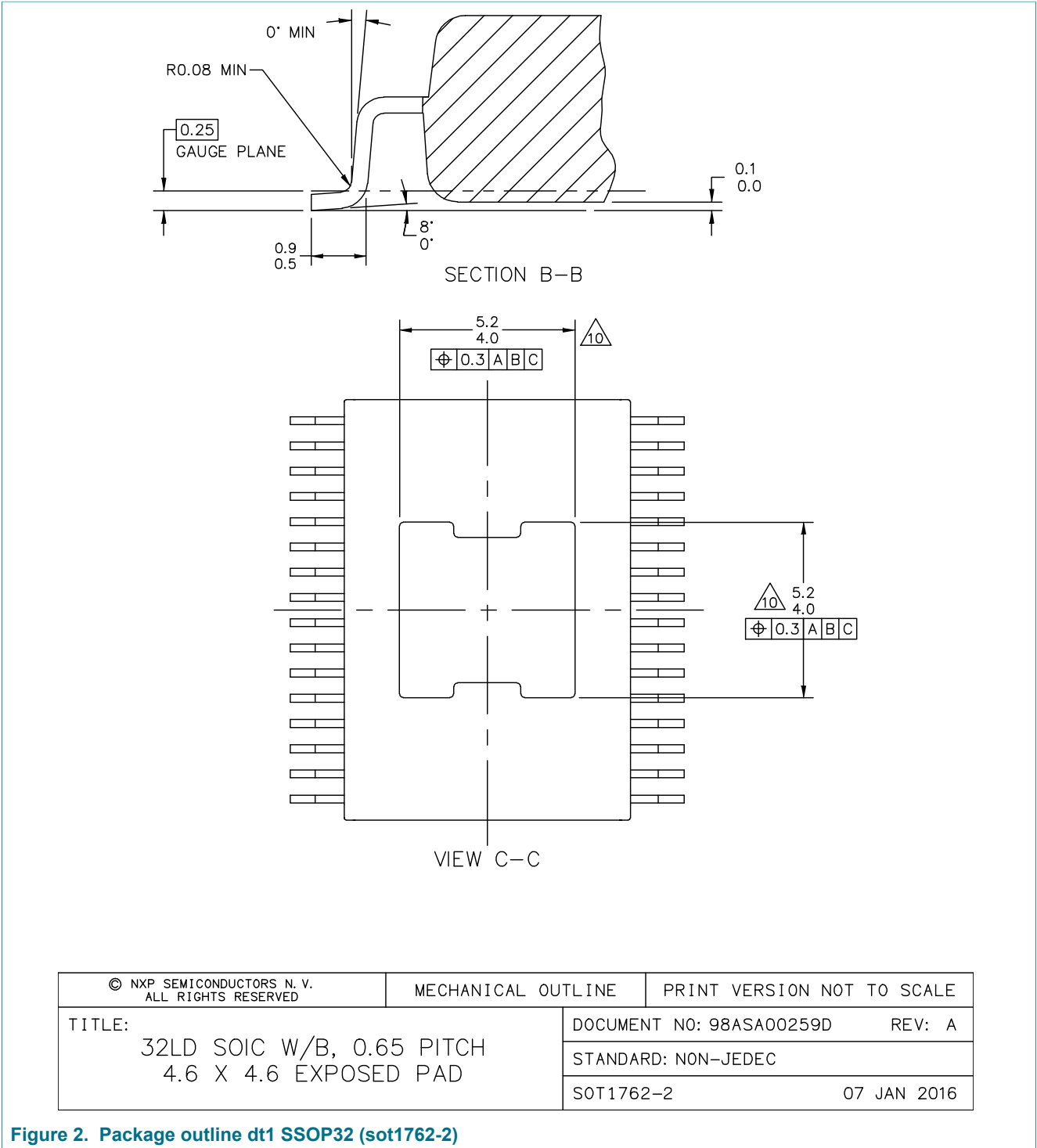


Figure 2. Package outline dt1 SSOP32 (sot1762-2)

SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
10. THESE DIMENSION RANGES DEFINE THE PRIMARY PCB KEEP-OUT AREA. MOLD LOCKING AND RESIN BLEED CONTROL FEATURES MAY BE VISIBLE.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 32LD SOIC W/B, 0.65 PITCH 4.6 X 4.6 EXPOSED PAD	DOCUMENT NO: 98ASA00259D	REV: A
	STANDARD: NON-JEDEC	
	SOT1762-2	07 JAN 2016

Figure 3. Package outline note SSOP32 (sot1762-2)

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

SSOP32; plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

Contents

1 Package summary1
2 Package outline2
3 Legal information5